

N-Channel Enhancement Mode Power MOSFET

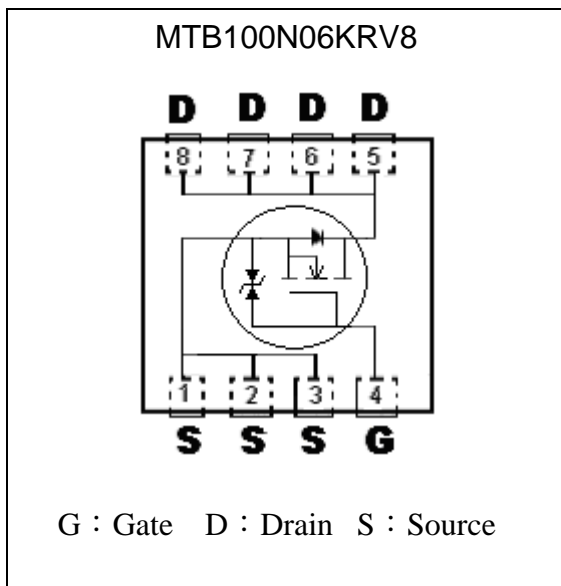
MTB100N06KRV8

BV_{DSS}	60V	
$I_D @ V_{GS}=10V, T_A=25^\circ C$	3.6A	
$I_D @ V_{GS}=10V, T_C=25^\circ C$	9A	
$R_{DSON(TYP)}$	$V_{GS}=10V, I_D=3A$	83mΩ

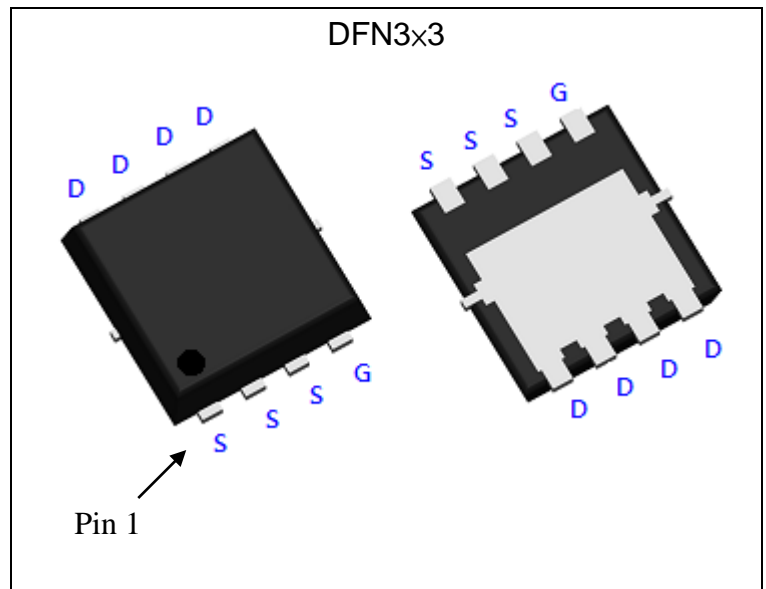
Features

- Simple Drive Requirement
- Low On-resistance
- Fast Switching Characteristic
- ESD protected gate
- Pb-free lead plating and halogen-free package

Equivalent Circuit

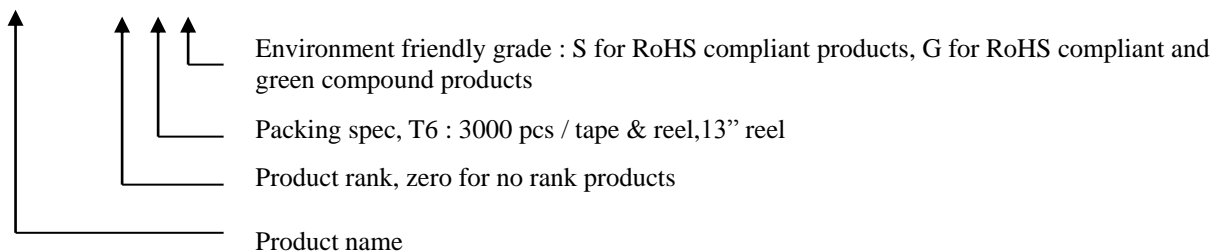


Outline



Ordering Information

Device	Package	Shipping
MTB100N06KRV8-0-T6-G	DFN3x3 (Pb-free lead plating and halogen-free package)	3000 pcs / tape & reel





Absolute Maximum Ratings (Ta=25°C, unless otherwise specified)

Parameter	Symbol	Limits	Unit	
Drain-Source Voltage	V _{DS}	60	V	
Gate-Source Voltage	V _{GS}	±20		
Continuous Drain Current @ V _{GS} =10V, T _C =25°C	I _D	9	A	
Continuous Drain Current @ V _{GS} =10V, T _C =70°C		7.2		
Continuous Drain Current @ V _{GS} =10V, T _A =25°C		3.6		
Continuous Drain Current @ V _{GS} =10V, T _A =70°C		2.9		
Pulsed Drain Current	I _{DM}	18 *1		
Total Power Dissipation	P _D	T _C =25°C	15.6	W
		T _C =100°C	6.2	
	P _{DSM}	T _A =25°C	2.5 *2	
		T _A =70°C	1.6 *2	
Operating Junction and Storage Temperature Range	T _j , T _{stg}	-55~+150	°C	

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	R _{θJC}	8	°C/W
Thermal Resistance, Junction-to-ambient, max	R _{θJA}	50 *2	

Note : 1. Pulse width limited by maximum junction temperature.
 2. Surface mounted on a 1 in² pad of 2oz copper, t ≤ 5s. In practice R_{th,j-a} will be determined by customer's PCB characteristics. 125°C/W when mounted on a minimum pad of 2 oz. copper.

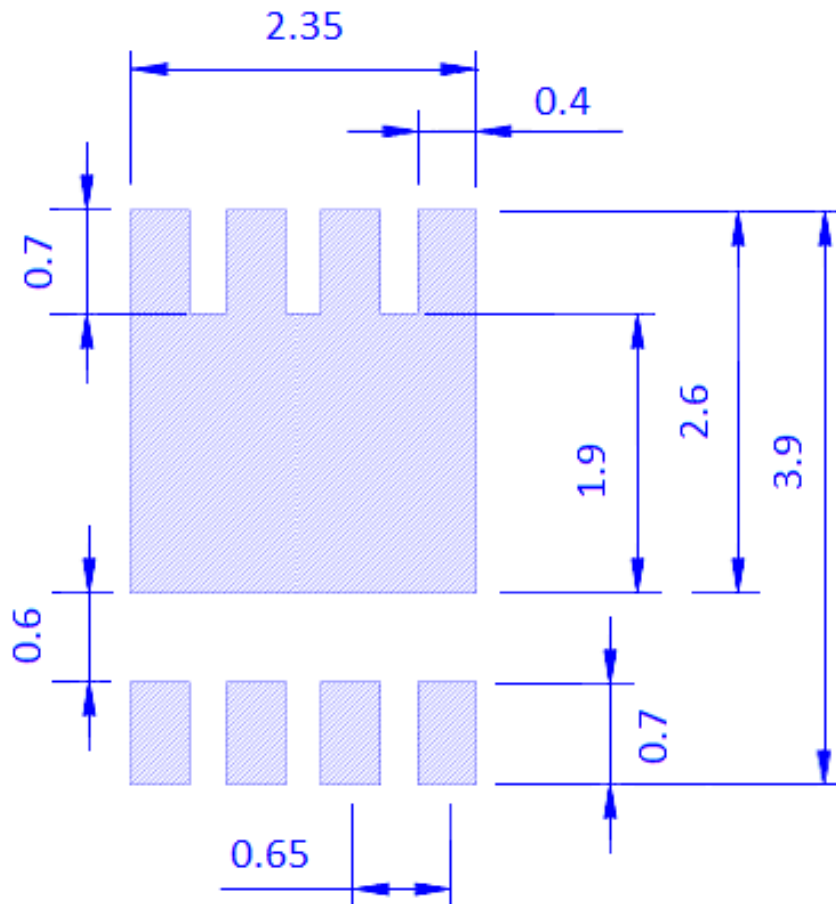
Characteristics (Tc=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	60	-	-	V	V _{GS} =0V, I _D =250μA
V _{GS(th)}	1	-	2.5		V _{DS} = V _{GS} , I _D =250μA
G _{FS} *1	-	3.1	-	S	V _{DS} =5V, I _D =3A
I _{GSS}	-	-	±10	μA	V _{GS} =±16V, V _{DS} =0V
I _{DSS}	-	-	10		V _{DS} =60V, V _{GS} =0V
	-	-	250		V _{DS} =48V, V _{GS} =0V, T _j =85°C
R _{DS(ON)} *1	-	83	120	mΩ	V _{GS} =10V, I _D =3A
	-	141	198		V _{GS} =4.5V, I _D =2.5A
Dynamic					
C _{iss}	-	121	-	pF	V _{DS} =30V, V _{GS} =0V, f=1MHz
C _{oss}	-	40	-		
C _{rss}	-	19	-		
Q _g *1,2	1.5	3	6	nC	V _{DS} =30V, V _{GS} =10V, I _D =3A
Q _{gs} *1,2	-	0.6	-		
Q _{gd} *1,2	-	0.6	-		

$t_{d(ON)}$ *1, 2	-	3.4	-	ns	$V_{DS}=30V, I_D=3A, V_{GS}=10V, R_{GS}=1\ \Omega$
t_r *1, 2	-	15.4	-		
$t_{d(OFF)}$ *1, 2	-	9.4	-		
t_f *1, 2	-	4	-		
R_g	-	9.9	-	Ω	$f=1MHz$
Source-Drain Diode					
I_S *1	-	-	9	A	
I_{SM} *3	-	-	18		
V_{SD} *1	-	0.83	1	V	$I_S=1A, V_{GS}=0V$
t_{rr}	-	7.5	-	ns	$I_F=3A, dI_F/dt=100A/\mu s$
Q_{rr}	-	2.9	-	nC	

Note : *1.Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
 *2.Independent of operating temperature
 *3.Pulse width limited by maximum junction temperature.

Recommended Soldering Footprint

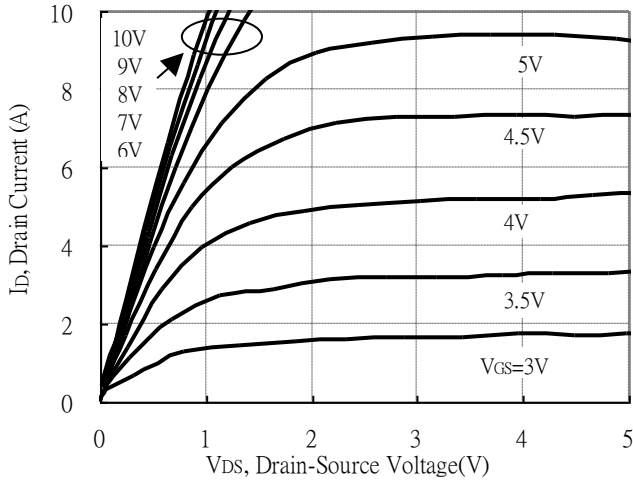


unit : mm

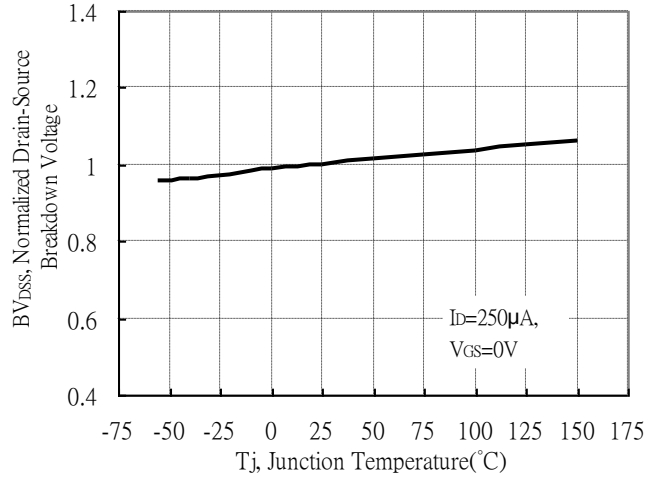


Typical Characteristics

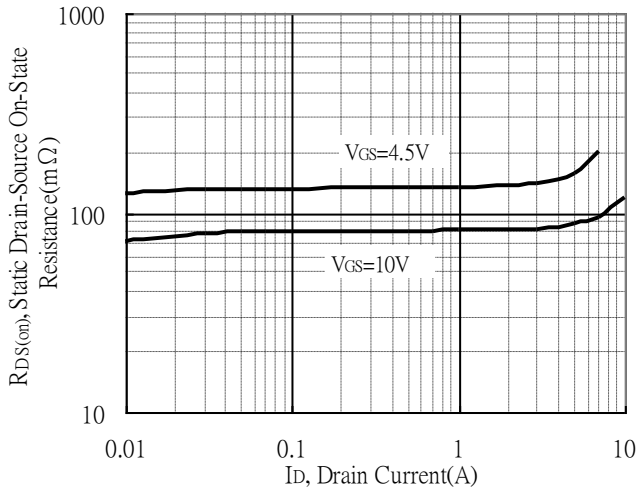
Typical Output Characteristics



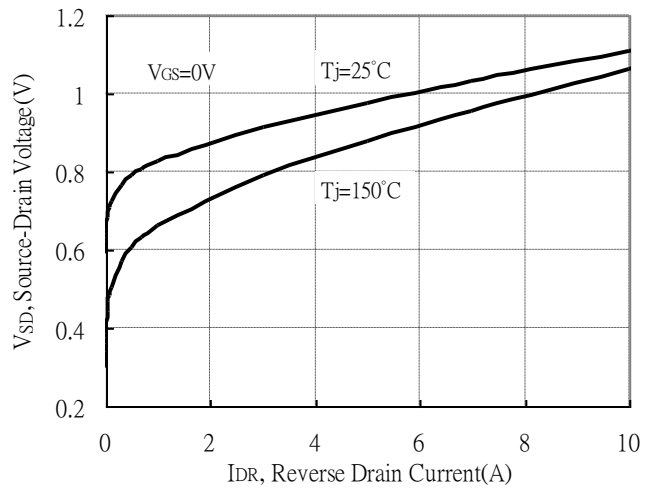
Brekdown Voltage vs Junction Temperature



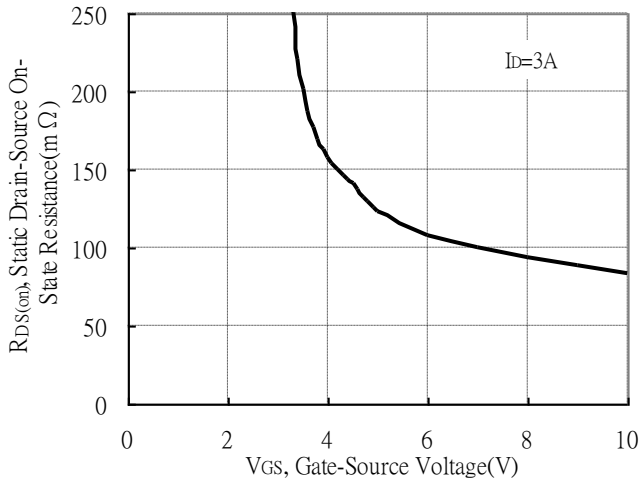
Static Drain-Source On-State resistance vs Drain Current



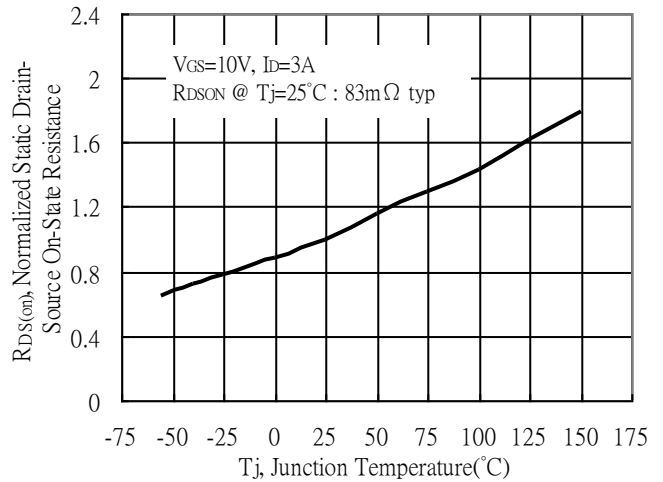
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage



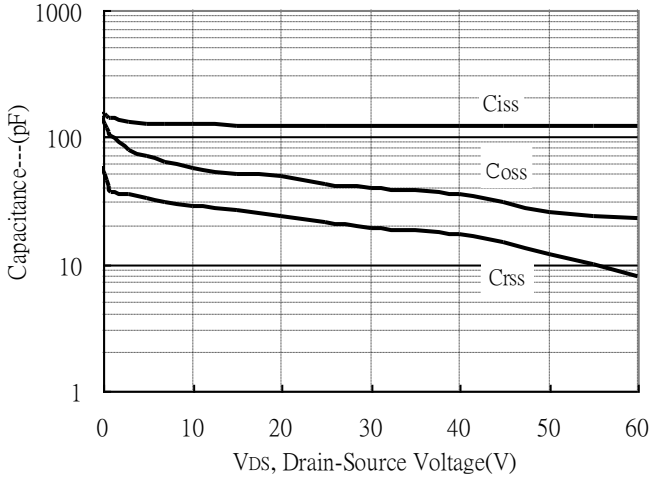
Drain-Source On-State Resistance vs Junction Temperature



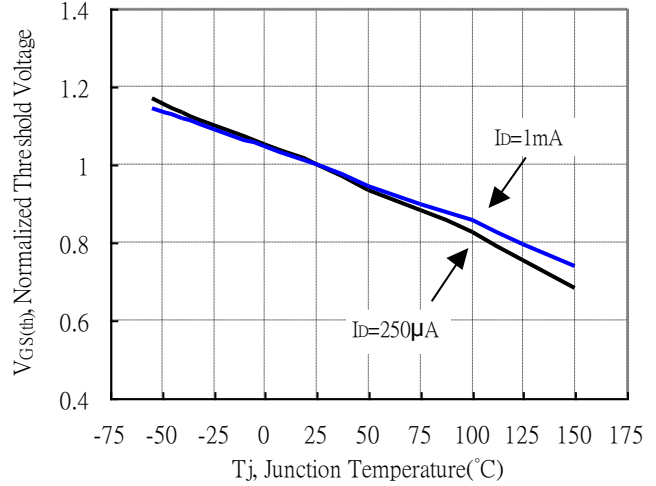


Typical Characteristics(Cont.)

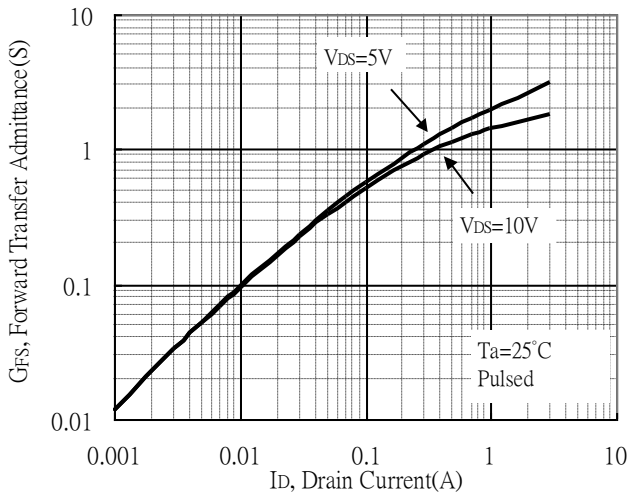
Capacitance vs Drain-to-Source Voltage



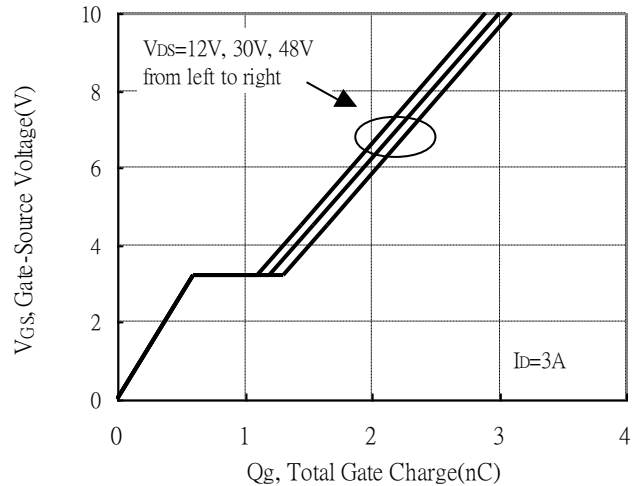
Threshold Voltage vs Junction Temperature



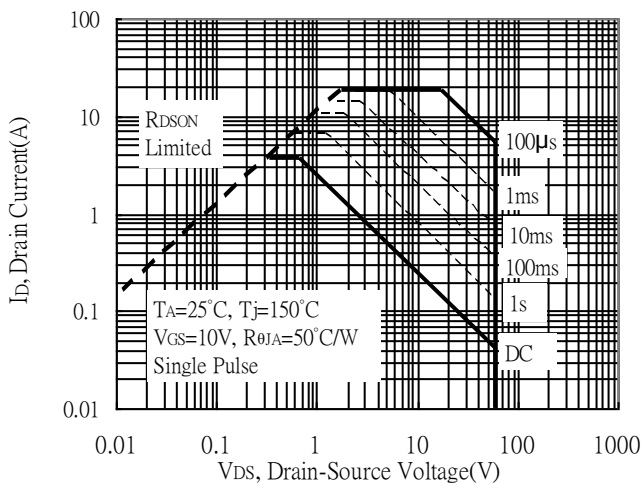
Forward Transfer Admittance vs Drain Current



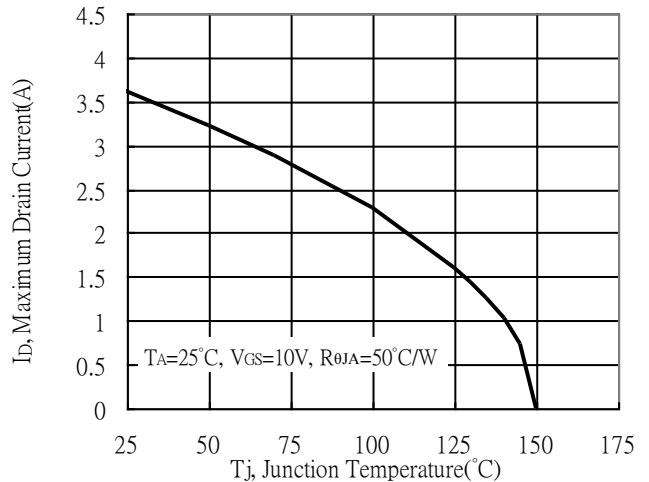
Gate Charge Characteristics



Maximum Safe Operating Area



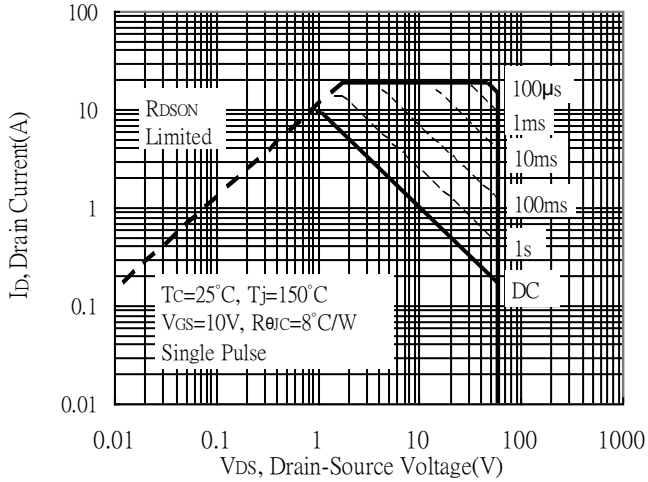
Maximum Drain Current vs Junction Temperature



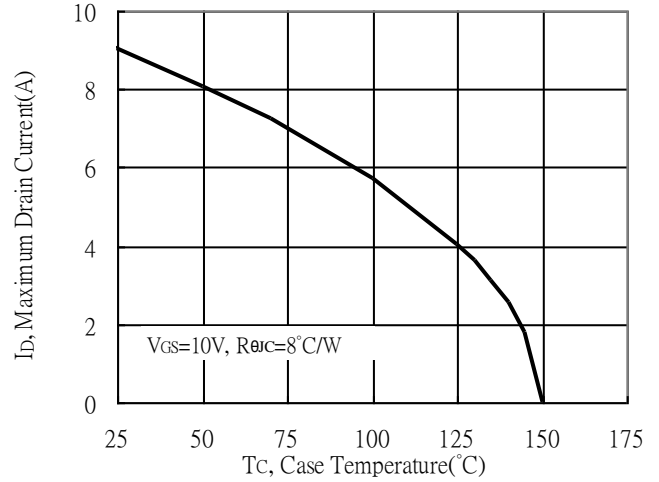


Typical Characteristics(Cont.)

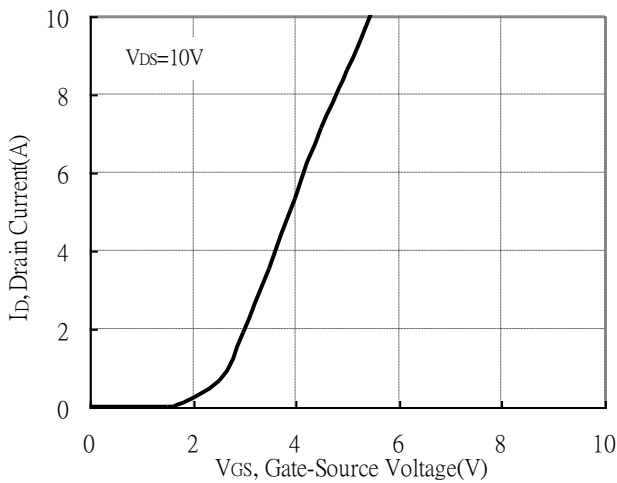
Maximum Safe Operating Area



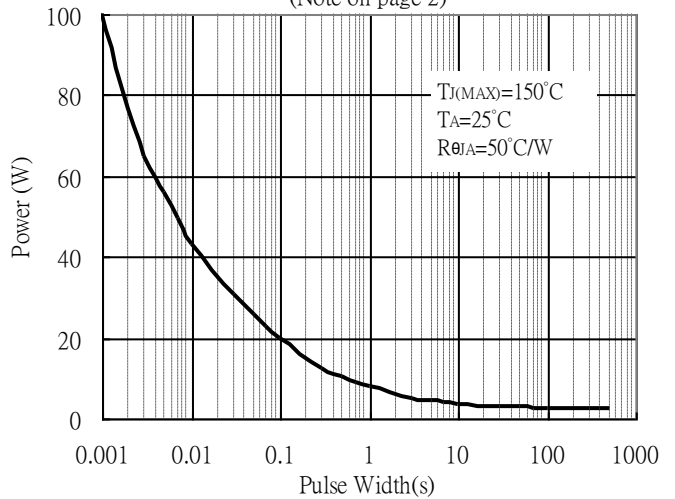
Maximum Drain Current vs Case Temperature



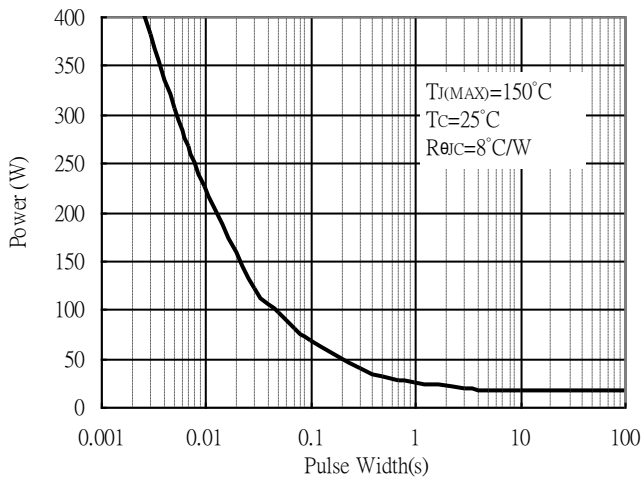
Typical Transfer Characteristics



Single Pulse Power Rating, Junction to Ambient
(Note on page 2)

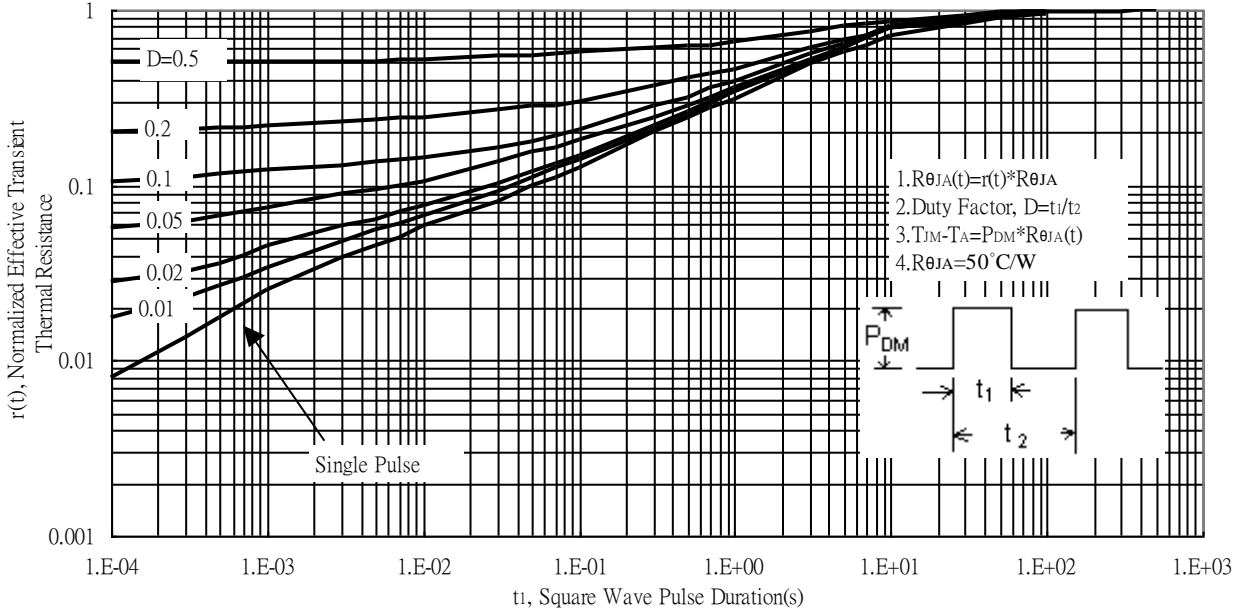


Single Pulse Power Rating, Junction to Case

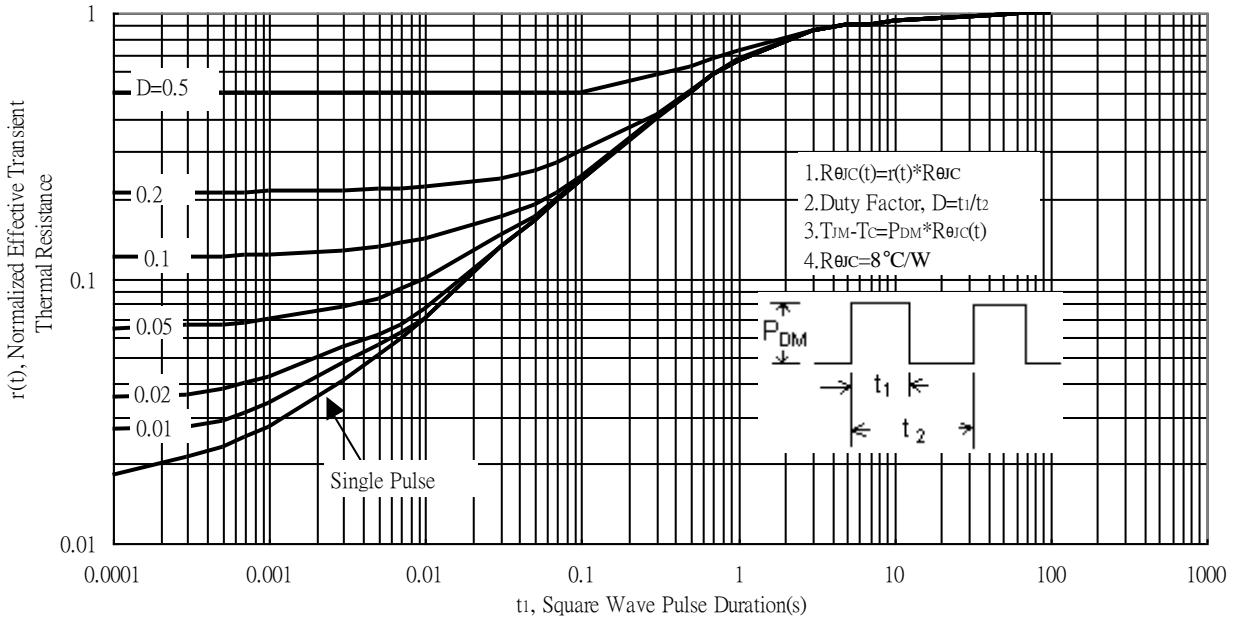


Typical Characteristics(Cont.)

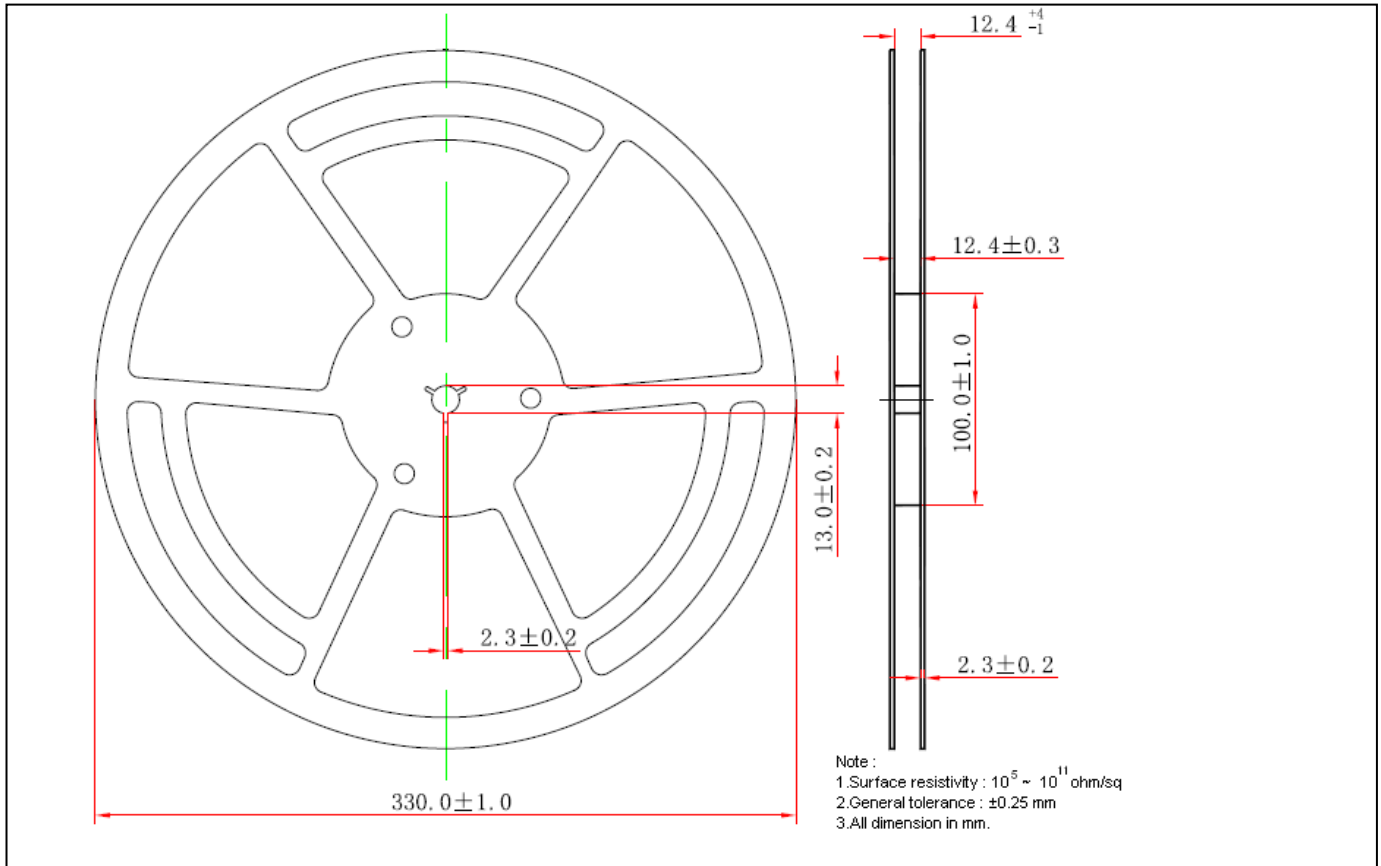
Transient Thermal Response Curves



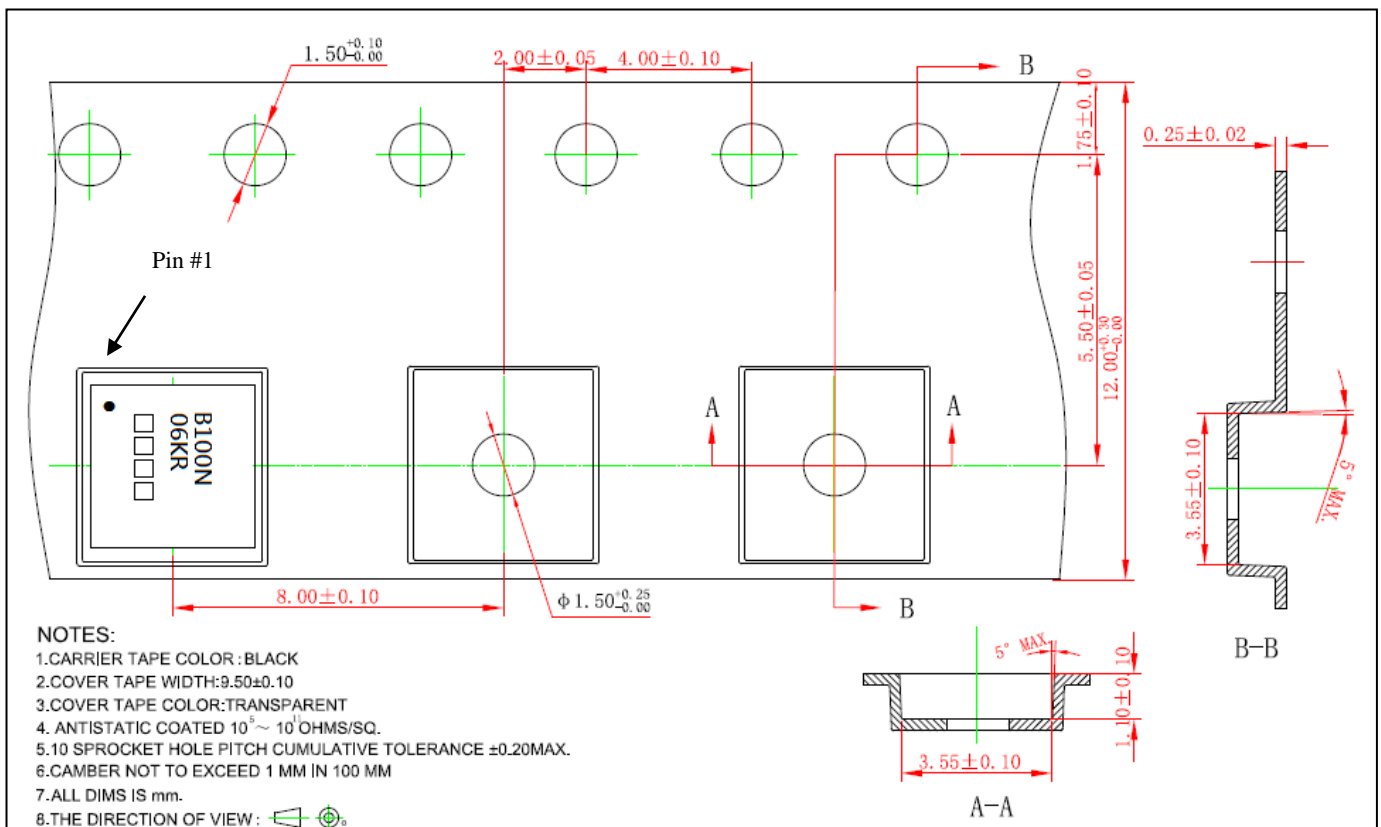
Transient Thermal Response Curves



Reel Dimension



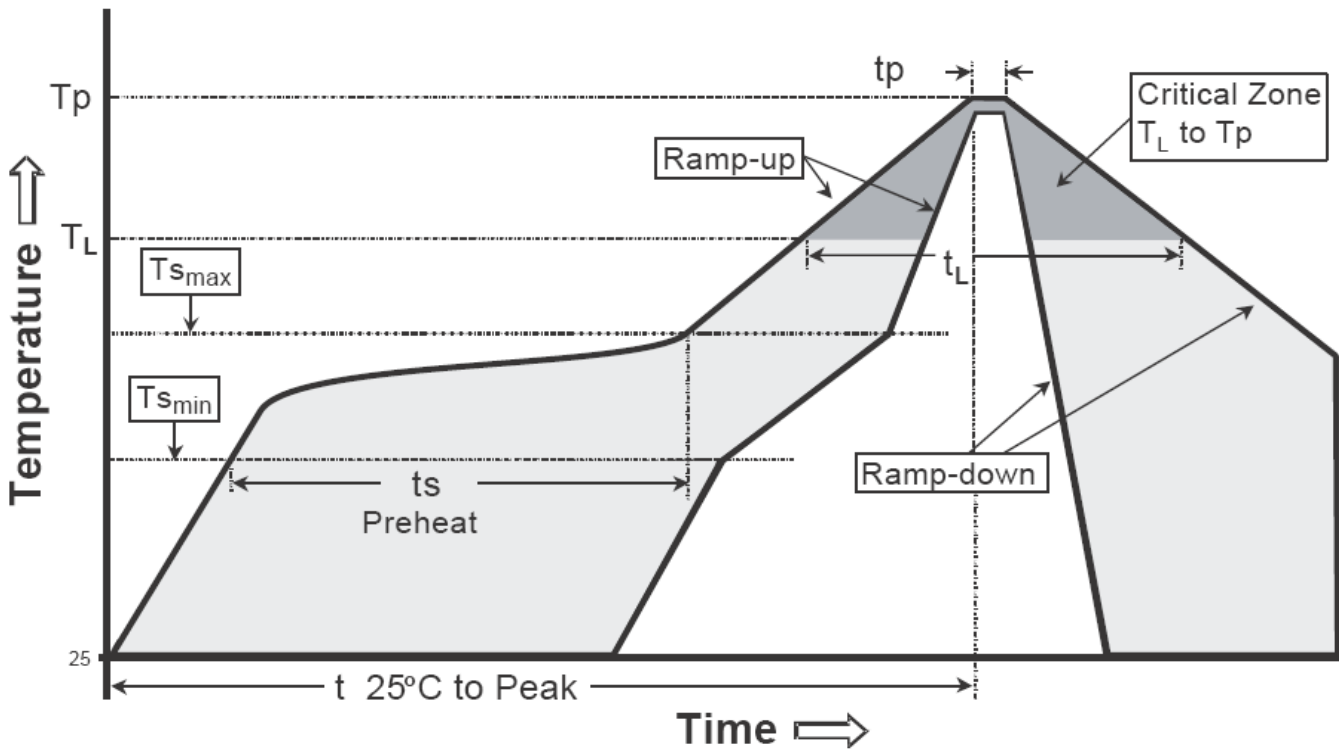
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

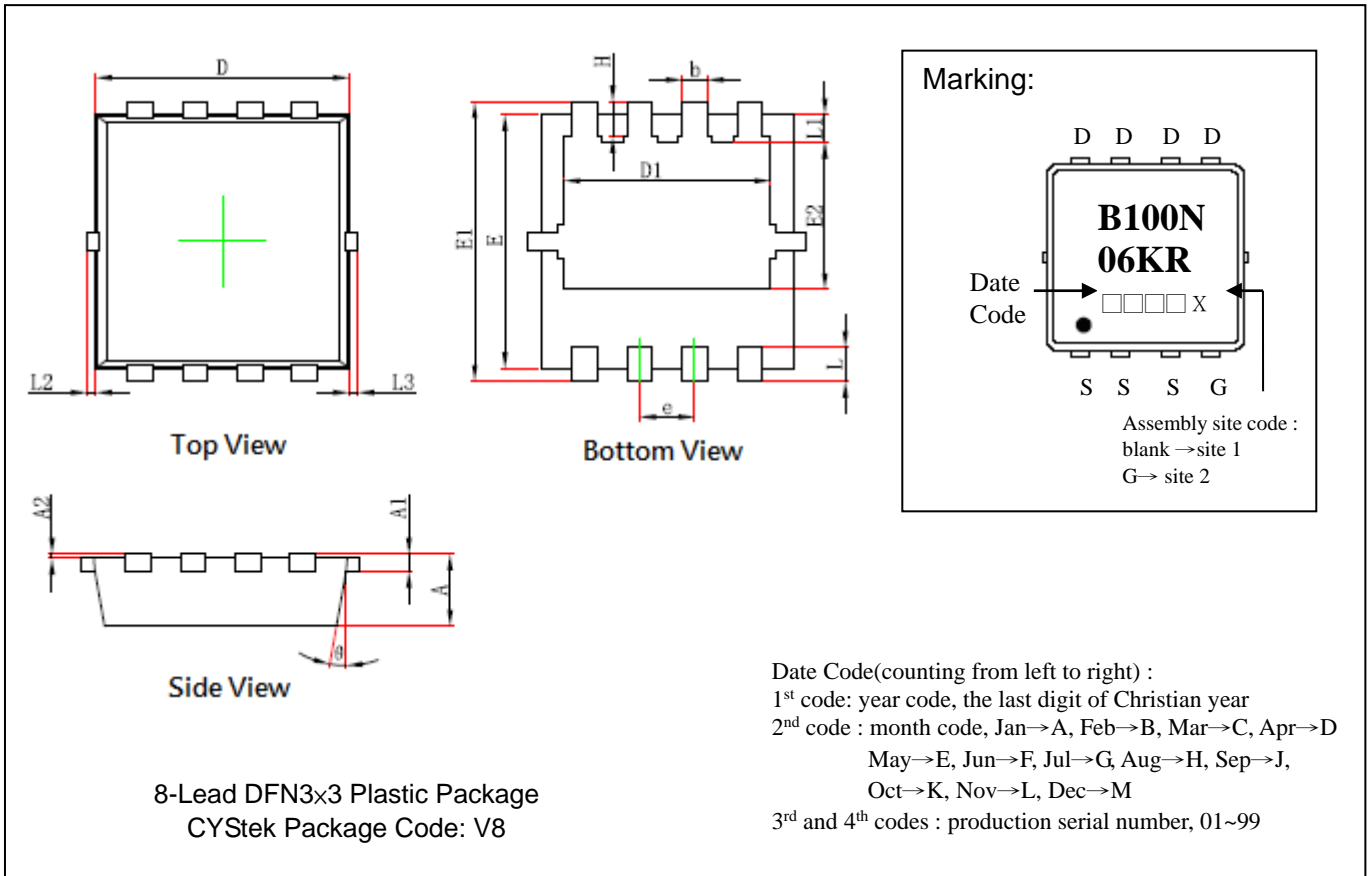
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _p)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

DFN3x3 Dimension



8-Lead DFN3x3 Plastic Package
 CYStek Package Code: V8

Marking:

D D D D
B100N
06KR
 Date Code → □□□□ X
 S S S G
 Assembly site code :
 blank → site 1
 G → site 2

Date Code(counting from left to right) :
 1st code: year code, the last digit of Christian year
 2nd code : month code, Jan→A, Feb→B, Mar→C, Apr→D
 May→E, Jun→F, Jul→G, Aug→H, Sep→J,
 Oct→K, Nov→L, Dec→M
 3rd and 4th codes : production serial number, 01~99

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.026	0.033	0.650	0.850	b	0.008	0.016	0.200	0.400
A1	0.006	REF	0.152	REF	e	0.022	0.030	0.550	0.750
A2	0.000	0.002	0.000	0.050	L	0.012	0.020	0.300	0.500
D	0.114	0.126	2.900	3.200	L1	0.007	0.019	0.180	0.480
D1	0.091	0.102	2.300	2.600	L2	0.000	0.006	0.000	0.150
E	0.114	0.126	2.900	3.200	L3	0.000	0.006	0.000	0.150
E1	0.124	0.136	3.150	3.450	H	0.012	0.020	0.300	0.515
E2	0.058	0.076	1.480	1.935	θ	8°	13°	8°	13°

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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